

Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.9)
LeadCount	44
Option	Pb-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Silica	72.61	2.72 E-01	529091
Epoxy, Cresol Novolac	19.36	7.24 E-02	141071
Phenol Resin	4.84	1.81 E-02	35268
Antimony Trioxide	1.45	5.42 E-03	10566
Brominated Epoxy Resin	1.45	5.42 E-03	10566
Carbon Black	0.29	1.08 E-03	2113
Subtotal		3.74 E-01	728675

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	195043
Ni	3.00	3.12 E-03	6081
Si	0.65	6.73 E-04	1310
Mg	0.15	1.58 E-04	307
Subtotal		1.04 E-01	202741

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100.0	1.03 E-03	2007

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100.0	6.15 E-03	11977

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	1.22 E-03	2385

Chip			
	% of Chip	Weight (g)	PPM
Si	100.0	2.32 E-02	45142

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	75.47	2.74 E-03	5338
Epoxy resin	18.87	6.85 E-04	1335
Gamma Butyrolactone	2.83	1.03 E-04	200
Curing agent & hardener	2.83	1.03 E-04	200
Subtotal		3.63 E-03	7073

Molding Compound		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321, ICP-OES
Cd	None Detected	Draft IEC 62321, ICP-OES
Hg	None Detected	Draft IEC 62321, ICP-OES
Cr+6	None Detected	Draft IEC 62321, UV-VIS.
PBB	None Detected	Draft IEC 62321, GC-MS.
PBDE	None Detected	Draft IEC 62321, GC-MS.

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321, ICP-OES
Cd	None Detected	Draft IEC 62321, ICP-OES
Hg	None Detected	Draft IEC 62321, ICP-OES
Cr+6	None Detected	Draft IEC 62321, UV-VIS.
PBB	None Detected	Draft IEC 62321, GC-MS.
PBDE	None Detected	Draft IEC 62321, GC-MS.

Package Totals	
Weight (g)	PPM
5.13 E-01	1000000

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Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.9)
LeadCount	44
Option	Sn/Pb

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Silica	72.61	2.72 E-01	529057
Epoxy, Cresol Novolac	19.36	7.24 E-02	141062
Phenol Resin	4.84	1.81 E-02	35266
Antimony Trioxide	1.45	5.42 E-03	10585
Brominated Epoxy Resin	1.45	5.42 E-03	10595
Carbon Black	0.29	1.06 E-03	2113
Subtotal		3.74 E-01	728628

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	195030
Ni	3.00	3.12 E-03	6081
Si	0.65	6.73 E-04	1310
Mg	0.15	1.58 E-04	307
Subtotal		1.04 E-01	202728

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100.0	1.03 E-03	2006

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	5.25 E-03	10239
Pb	15	9.27 E-04	1806
Subtotal		6.18 E-03	12041

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.22 E-03	2385

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	2.32 E-02	45139

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	75.47	2.74 E-03	5338
Epoxy resin	18.87	6.85 E-04	1335
Gamma Butyrolactone	2.83	1.03 E-04	200
Curing agent & hardener	2.83	1.03 E-04	200
Subtotal		3.63 E-03	7073

Package Totals		
Weight (g)	PPM	
5.13 E-01	1000000	

Molding Compound		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

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Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.9)
LeadCount	44
Option	Pb-free, Halide-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.91	3.25 E-01	634487
Epoxy & Phenol Resin	12.78	4.78 E-02	93300
Carbon black	0.31	1.16 E-03	2263
Subtotal		3.74 E-01	730050

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	195405
Ni	3.00	3.12 E-03	6094
Si	0.65	6.76 E-04	1320
Mg	0.15	1.56 E-04	305
Subtotal		1.04 E-01	203124

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100.0	1.03 E-03	2010

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100.0	6.15 E-03	12000

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.41 E-03	2754

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	2.22 E-02	43266

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	75.5	2.63 E-03	5129
Epoxy resin	18.9	6.57 E-04	1282
Gamma Butyrolactone	2.8	9.85 E-05	192
Curing agent & hardener	2.8	9.85 E-05	192
Subtotal		3.48 E-03	6795

Molding Compound		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Package Totals

Weight (g)	PPM
5.12 E-01	1000000

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Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.9)
LeadCount	44
Option	with Pb, Halide-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.91	3.25 E-01	634487
Epoxy & Phenol Resin	12.78	4.78 E-02	93300
Carbon black	0.31	1.16 E-03	2263
Subtotal		3.74 E-01	730050

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	195405
Ni	3.00	3.12 E-03	6094
Si	0.65	6.76 E-04	1320
Mg	0.15	1.56 E-04	305
Subtotal		1.04 E-01	203124

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100.0	1.03 E-03	2010

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	5.22 E-03	10200
Pb	15	9.22 E-04	1800
Subtotal		6.15 E-03	12000

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.41 E-03	2754

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	2.22 E-02	43266

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	75.5	2.63 E-03	5129
Epoxy resin	18.9	6.57 E-04	1282
Gamma Butyrolactone	2.8	9.85 E-05	192
Curing agent & hardener	2.8	9.85 E-05	192
Subtotal		3.48 E-03	6795

Package Totals		
Weight (g)	PPM	
5.12 E-01	1000000	

Molding Compound		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

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